

What is claimed is:

1. A jig for holding and conveyance comprising:
  - a plate having a weak-adherence adhesive pattern on its surface; and
    - a printed circuit board having a conductive portion and a non-conductive portion on its surface, or a conductive material laminated plate for manufacturing said printed circuit board, said printed circuit board or said conductive material laminated plate being placed and held on the surface of said plate,
      - wherein said weak-adherence adhesive pattern is formed at a position corresponding to said non-conductive portion.
2. A jig for holding and conveyance comprising:
  - a plate having a weak-adherence adhesive layer on its surface; and
    - a printed circuit board having a conductive portion and a non-conductive portion on its surface, or a conductive material laminated plate for manufacturing said printed circuit board, said printed circuit board or said conductive material laminated plate being placed and held on the surface of said plate,
      - wherein a weak-adherence adhesive pattern subjected to surface roughening is formed on a surface of said weak-adherence adhesive layer at a position corresponding to said conductive portion.

3. The jig for holding and conveyance according to claim 1 or 2, wherein said weak-adherence adhesive pattern has a plurality of thickness regions differing in thickness from the surface of said plate.

4. The jig for holding and conveyance according to any one of claims 1 to 3, wherein said weak-adherence adhesive pattern has a plurality of adhesive strength regions differing in adhesive strength.

5. The jig for holding and conveyance according to claim 2, wherein a non-adhesive pattern is formed at a position corresponding to said conductive portion on the surface of said weak-adherence adhesive layer.

6. A method of conveying a printed circuit board having a conductive portion and a non-conductive portion on its surface while holding said printed circuit board on a jig for holding and conveyance, said jig having a weak-adherence adhesive pattern provided on its surface,

wherein when said printed circuit board is held on the surface of said jig for holding and conveyance, said non-conductive portion is placed by being restricted to a surface of said weak-adherence adhesive pattern.

7. A method of conveying an electroconductive material laminated plate for manufacturing a printed circuit board having a conductive portion and a non-conductive portion on its surface while holding said electroconductive material laminated plate on a jig for holding and conveyance, said jig

having a weak-adherence adhesive pattern provided on its surface,

wherein when said electroconductive material laminated plate is held on the surface of said jig for holding and conveyance, a portion intended for formation of said non-conductive portion is placed by being restricted to a surface of said weak-adherence adhesive pattern.

8. A jig for holding and conveyance comprising:

a plate having a weak-adherence adhesive layer on its surface;

a printed circuit board having a conductor pattern on its insulating substrate surface, or an electroconductive material laminated plate for manufacturing said printed circuit board, said printed circuit board or said electroconductive material laminated plate being placed and held on the surface of said plate,

wherein said weak-adherence adhesive layer is a fluorine-based resin layer.

9. The jig for holding and conveyance according to claim 8, wherein said fluorine-based resin layer is formed so as to hold said printed circuit board or said electroconductive material laminated plate so that a surface of said conductor pattern or an electroconductive material foil surface of said electroconductive material laminated plate is approximately parallel to the surface of said plate.

10. The jig for holding and conveyance according to claim 8 or 9, wherein said fluorine-based resin layer has a plurality

of thickness regions differing in thickness from the surface of said plate.

11. The jig for holding and conveyance according to any one of claims 8 to 10, wherein said fluorine-based resin layer has a plurality of adhesive strength regions differing in adhesive strength.

12. The jig for holding and conveyance according to any one of claims 8 to 11, wherein surface roughening is selectively performed on a region of said fluorine-based resin layer other than a holding portion for holding said printed circuit board or said electroconductive material laminated plate.

13. The jig for holding and conveyance according to any one of claims 8 to 11, wherein a plurality of said fluorine-based resin layers are provided on the surface of said plate, and a non-adhesive material layer is provided on a non-formation portion of said fluorine-based resin layers on the surface of said plate.

14. The jig for holding and conveyance according to any one of claims 8 to 11, wherein said fluorine-based resin layer has a holding portion for holding said printed circuit board or said electroconductive material laminated plate, and has a non-adhesive layer on a portion other than said holding portion.

15. The jig for holding and conveyance according to any one of claims 8 to 14, wherein said fluorine-based resin layer has a hardness (JIS-A) of 100° or lower.